Flow And Heat Transfer Simulations As A **Development Tool For A Novel Microcalorimeter**

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INTRODUCTION

In this study, we used version 5.3a of the simulation software COMSOL Multiphysics® as a development tool for a novel microcalorimeter. Our simulation results give us a comprehensive insight into the 3Dtemperature distribution of the entire system. As a result, we can comprehend all heat flow pattern that cannot be measured experimentally. In this way, we cannot only improve the performance of the microcalorimeter but also expand our understanding of heat transfers within microcalorimeter.



Figure 1: Cross-section of the 3D-COMSOL model.

A: air heater. B: upper channel part. C: lower channel part. D: primary heat sink. E: thermoelectric cooler (T.E.C). F: interior air domain. G: heat flow sensors (HFS). H: auxiliary heat sink. I: interior fan. J: housing. K: temperature probes.

Red arrows - flow direction. Not shown here are the two heating foils below the heat sink D.

COMPUTATIONAL METHODS

The simplified 3D-model simulates in a first stationary study step the laminar flow caused by an interior fan. Subsequently, the heat transfer is simulated in a time-dependent study step. Both interfaces are connected via the nonisothermal multiphysics interface. Additionally, ODE and DAE interfaces (Events and Global ODE and DAE Interface) are applied to simulate the temperature control unit.

laminar flow



temperature regulation



Figure 4: Cross-sections of different areas within the 3D-COMSOL model. Left: xz-plane through the air heater. Air domain is heated by an air heater source (electrical resistor). Center: temperature of the primary heat sink has to be kept constant (T_{set} = 310.22 K). This temperature is regulated by two thermoelectric coolers (T.E.Cs) via a PID controller, using the temperature probe as input. **Right:** the interior air domain is surrounded by housing plates. The external temperature (T_{ext}) is 293.15 K and the heat transfer coefficient (h) is 5 W/(m² K). Blue area - interior air domain. Red lines - heat fluxes in the respective plane.

Boundary conditions